

### Description

The DFH300AL12E4C1 is a 3-level Power Module. It integrates 1200V SiC MOSFET chips and 1200V IGBT chips designed for the applications such as Solar Inverter, High frequency switching, Energy storage Systems etc.



### Features

- Blocking voltage:1200V
- $R_{ds(on)}$ : 4.3m $\Omega$  @  $V_{GS} = 18V$
- Low Switching Losses
- High current density
- Press FIT Contact Technology
- 175°C maximum junction temperature
- Thermistor inside

### Applications

- Solar inverter Systems
- Three-level applications
- Energy Storage Systems
- High Frequency Switching application

### Circuit diagram

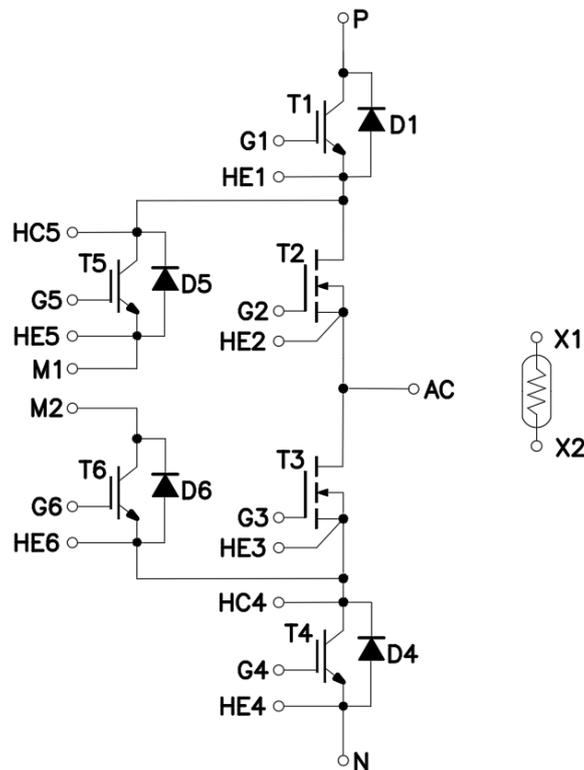


Figure 1. Out drawing & circuit diagram for DFH300AL12E4C1

### Pin Configuration

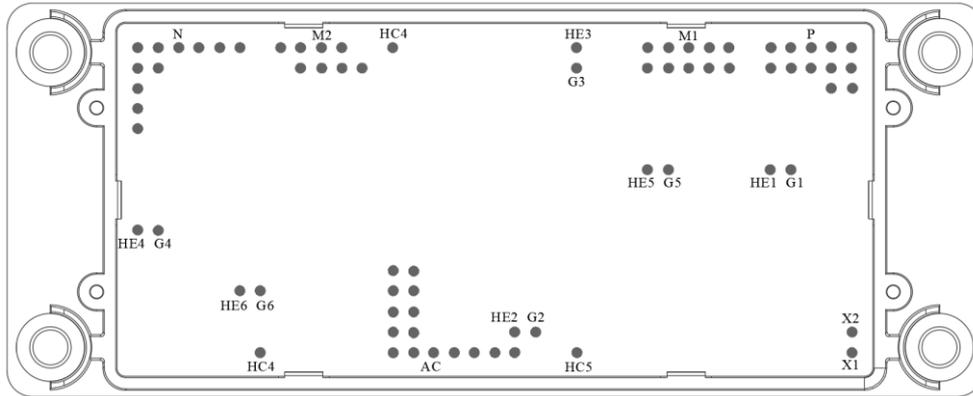


Figure 2. Pin configuration

### Module

Parameter	Conditions	Value	Unit
Isolation voltage	Main terminal to base plate, RMS, $f = 50\text{Hz}$ , $t = 1\text{min}$	3.4	kV
Creepage distance	terminal to heatsink	11.2	mm
	terminal to terminal	6.8	
Clearance	terminal to heatsink	9.4	
	terminal to terminal	5.5	
Comparative tracking index	-	> 400	
Mounting torque for module mounting	Screw M5 baseplate to heatsink	1.3 to 1.5	Nm
Storage temperature	-	-40 to 125	°C
Weight	-	125	g

### NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
$R_{25}$	Resistance	$T_C = 25^\circ\text{C}$	-	5	-	k $\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_C = 100^\circ\text{C}$ , $R_{100} = 493\Omega$	-5	-	5	%
$P_{25}$	Power dissipation	$T_C = 25^\circ\text{C}$	-	-	20	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

### Maximum Ratings (T2/T3: SiC MOSFET, $T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
$V_{DSS}$	Drain-Source Voltage	G-S Short	1200	V
$V_{GSS}$	G-S Voltage	D-S Short, Note1	-8 to 22	V
$I_{DS}$	DC Continuous Drain Current	$T_S=65^\circ\text{C}$	275	A
$I_{SD}$	Source (Body diode) Current	-	275	A
$I_{DP}$	Drain Pulse Current, Peak	Less than 1ms, Note2	600	A
$T_j$	junction temperature	-	-40 to 175	$^\circ\text{C}$

Note1: Recommended Operating Value, +18V/-4V, +15V/-4V

### Maximum Ratings (T1/T4/T5/T6: IGBT, $T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
$V_{CES}$	Collector-Emitter Voltage	G-E Short	1200	V
$V_{GES}$	Gate-Emitter Voltage	C-E Short	$\pm 20$	V
$I_{CDC}$	DC Continuous Collector Current	$T_S=65^\circ\text{C}$ , $T_j=150^\circ\text{C}$	310	A
$I_{CM}$	Pulse Collector Current	$t_p=1\text{ms}$ , Note1	800	A
$P_C$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ , $T_j=175^\circ\text{C}$	1136	W
$T_j$	junction temperature	-	-40 to 175	$^\circ\text{C}$

Note1: Pulse width limited by maximum junction temperature

### Maximum Ratings (D1/D4/D5/D6: Diode, $T_j=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
$V_{RRM}$	Repetitive peak reverse Voltage	G-E Short	1200	V
$I_F$	Diode forward Current	-	300	A
$I_{FRM}$	Repetitive peak forward Current	$t_p=1\text{ms}$ , Note1	600	A
$T_j$	junction temperature	-	-40 to 175	$^\circ\text{C}$

Note1: Pulse width limited by maximum junction temperature

### T2/T3: SiC MOSFET Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=400\mu A$	1200	-	-	V	
$I_{DSS}$	Zero gate voltage drain Current	$V_{DS}=1200V, V_{GS}=0V$	-	-	400	$\mu A$	
$V_{GS(th)}$	Gate-source threshold Voltage	$I_D=80mA, V_{DS}=V_{GS}$	1.9	2.6	3.5	V	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=18V, V_{DS}=0V$	-	-	400	nA	
$R_{DS(on)}$ (Chip)	Static drain-source On-state resistance	$I_D=300A$ $V_{GS}=18V$	$T_j=25^\circ\text{C}$	-	4.3	7.5	m $\Omega$
			$T_j=175^\circ\text{C}$	-	8.0	-	m $\Omega$
$V_{DS(on)}$ (Chip)	Static drain-source On-state Voltage	$I_D=300A$ $V_{GS}=18V$	$T_j=25^\circ\text{C}$	-	1.29	2.25	V
			$T_j=175^\circ\text{C}$	-	2.40	-	V
$C_{iss}$	Input Capacitance	$V_D=1000V, V_{GS}=0V$ $f=1MHz$	-	18.8	-	nF	
$C_{oss}$	Output Capacitance		-	0.8	-	nF	
$C_{rss}$	Reverse transfer Capacitance		-	0.08	-	nF	
$Q_G$	Total gate charge	$V_{DD}=800V, I_D=200A, V_{GS}=0/+18V$	-	860	-	nC	
$R_{Gint}$	Internal Gate Resistance	$f=1MHz, V_{AC}=25mV$	-	0.15	-	$\Omega$	
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600V$ $I_D=300A$ $V_{GS}=+15V/-4V$ $R_g=5.0\Omega$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	37	-	ns
			$T_j=150^\circ\text{C}$	-	36	-	
$t_r$	Rise time		$T_j=25^\circ\text{C}$	-	48	-	ns
			$T_j=150^\circ\text{C}$	-	50	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ\text{C}$	-	82	-	ns
			$T_j=150^\circ\text{C}$	-	87	-	
$t_f$	Fall time		$T_j=25^\circ\text{C}$	-	25	-	ns
			$T_j=150^\circ\text{C}$	-	26	-	
$E_{on}$	Turn-on power dissipation		$T_j=25^\circ\text{C}$	-	6.75	-	mJ
			$T_j=150^\circ\text{C}$	-	8.74	-	
$E_{off}$	Turn-off power dissipation	$T_j=25^\circ\text{C}$	-	2.89	-	mJ	
		$T_j=150^\circ\text{C}$	-	3.59	-		
$R_{th(j-c)}$	FET Thermal Resistance	Junction to Case/MOSFET	-	0.082	-	K/W	
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied), Note1		-	0.10	-	K/W	

Note1: Assumes Thermal Conductivity of grease is 2.8W/m·K and thickness is 50 $\mu$ m.

### T2/T3: Body Diode Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_{SD}$	Body Diode Forward Voltage	$V_{GS}=-4V$ $I_{SD}=300A$	$T_j=25^\circ\text{C}$	-	5.0	-	V
			$T_j=175^\circ\text{C}$	-	3.9	-	
$T_{rr}$	Reverse recovery time	$V_{CC}=600V$ $I_D=300A$ $V_{GS}=+15/-4V$ $R_g=5.0\Omega$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	34	-	ns
			$T_j=150^\circ\text{C}$	-	48	-	
$Q_{rr}$	Reverse recovery charge		$T_j=25^\circ\text{C}$	-	0.69	-	$\mu C$
			$T_j=150^\circ\text{C}$	-	2.02	-	
$E_{rr}$	Diode switching power dissipation		$T_j=25^\circ\text{C}$	-	0.67	-	mJ
			$T_j=150^\circ\text{C}$	-	1.06	-	

### T1/T4/T5/T6: IGBT Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_{CE(sat)}$ (Chip)	Collector-Emitter Saturation Voltage	$I_C=300\text{A}$ $V_{GE}=15\text{V}$	$T_j=25^\circ\text{C}$	-	1.65	-	V
			$T_j=150^\circ\text{C}$	-	1.85	-	V
			$T_j=175^\circ\text{C}$	-	1.90	-	V
$V_{GE(th)}$	Gate-Emitter threshold Voltage	$I_C=11.4\text{mA}$ , $V_{CE}=V_{GE}$	5.0	5.6	6.8	V	
$Q_G$	Gate charge	$V_{GE}=-15\text{V}$ to $+15\text{V}$	-	2.2	-	$\mu\text{C}$	
$R_{Gint}$	Internal gate resistor	-	$T_j=25^\circ\text{C}$	-	2.5	-	$\Omega$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ $f=1\text{MHz}$	$T_j=25^\circ\text{C}$	-	26.0	-	nF
$C_{res}$	Reverse transfer Capacitance			-	0.93	-	nF
$I_{CES}$	Collector- Emitter Cut off Current	$V_{CE}=1200\text{V}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=-20\text{V}$ , $V_{CE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	0.75	$\mu\text{A}$
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600\text{V}$ $I_C=300\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ $R_g=1.0\Omega$ Inductive load	$T_j=25^\circ\text{C}$	-	168	-	ns
			$T_j=125^\circ\text{C}$	-	171	-	
			$T_j=175^\circ\text{C}$	-	179	-	
$t_r$	Rise time		$T_j=25^\circ\text{C}$	-	44	-	ns
			$T_j=125^\circ\text{C}$	-	47	-	
			$T_j=175^\circ\text{C}$	-	48	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^\circ\text{C}$	-	392	-	ns
			$T_j=125^\circ\text{C}$	-	421	-	
			$T_j=175^\circ\text{C}$	-	449	-	
$t_f$	Fall time		$T_j=25^\circ\text{C}$	-	90	-	ns
		$T_j=125^\circ\text{C}$	-	129	-		
		$T_j=175^\circ\text{C}$	-	159	-		
$E_{on}$	Turn-on power dissipation	$T_j=25^\circ\text{C}$	-	25.1	-	mJ	
		$T_j=125^\circ\text{C}$	-	33.2	-		
		$T_j=175^\circ\text{C}$	-	38.7	-		
$E_{off}$	Turn-off power dissipation	$T_j=25^\circ\text{C}$	-	21.3	-	mJ	
		$T_j=125^\circ\text{C}$	-	29.4	-		
		$T_j=175^\circ\text{C}$	-	35.7	-		
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (IGBT)			-	0.032	-	K/W
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.10	-	K/W

Note1: Assumes Thermal Conductivity of grease is  $2.8\text{W}/\text{m}\cdot\text{K}$  and thickness is  $50\mu\text{m}$ .

### D1/D4/D5/D6: Freewheeling Diode Electrical characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition	Value			Unit	
			Min.	Typ.	Max		
$V_F$	Diode Forward Voltage	$I_F=300\text{A}$ , $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	1.7	2.1	V
			$T_j=175^\circ\text{C}$	-	1.65	-	
$t_{rr}$	Reverse recovery time	(Switch side) $V_{CC}=600\text{V}$ $I_C=300\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ $R_g=1.0\Omega$	$T_j=25^\circ\text{C}$	-	0.30	-	us
			$T_j=125^\circ\text{C}$	-	0.57	-	
			$T_j=175^\circ\text{C}$	-	0.66	-	
$I_{RM}$	Peak reverse recovery Current	(FRD side) $V_{rr}=600\text{V}$ $I_F=300\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	280	-	A
			$T_j=125^\circ\text{C}$	-	259	-	
			$T_j=175^\circ\text{C}$	-	262	-	
$Q_{rr}$	Recovered charge	(FRD side) $V_{rr}=600\text{V}$ $I_F=300\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	22.6	-	uC
			$T_j=125^\circ\text{C}$	-	41.7	-	
			$T_j=175^\circ\text{C}$	-	56.5	-	
$E_{rr}$	Reverse recovered energy	(FRD side) $V_{rr}=600\text{V}$ $I_F=300\text{A}$ $V_{GE}=+15\text{V}/-8\text{V}$ Inductive load switching operation	$T_j=25^\circ\text{C}$	-	7.05	-	mJ
			$T_j=125^\circ\text{C}$	-	12.7	-	
			$T_j=175^\circ\text{C}$	-	17.9	-	
$R_{th(j-c)}$	Thermal Resistance, Junction to Case (Diode)		-	0.083	-	K/W	
$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied), Note1		-	0.10	-	K/W	

Note1: Assumes Thermal Conductivity of grease is  $2.8\text{W}/\text{m}\cdot\text{K}$  and thickness is  $50\mu\text{m}$ .

### Test Conditions

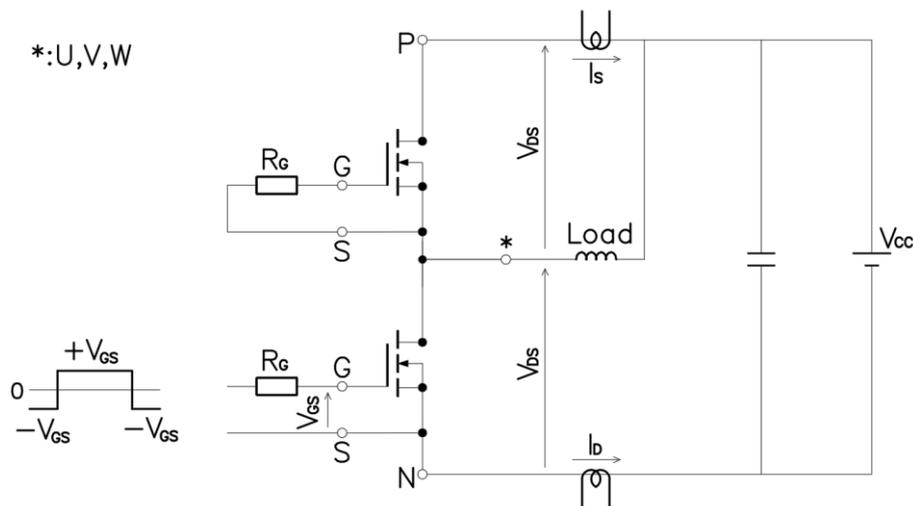


Figure 3. Switching time measure circuit

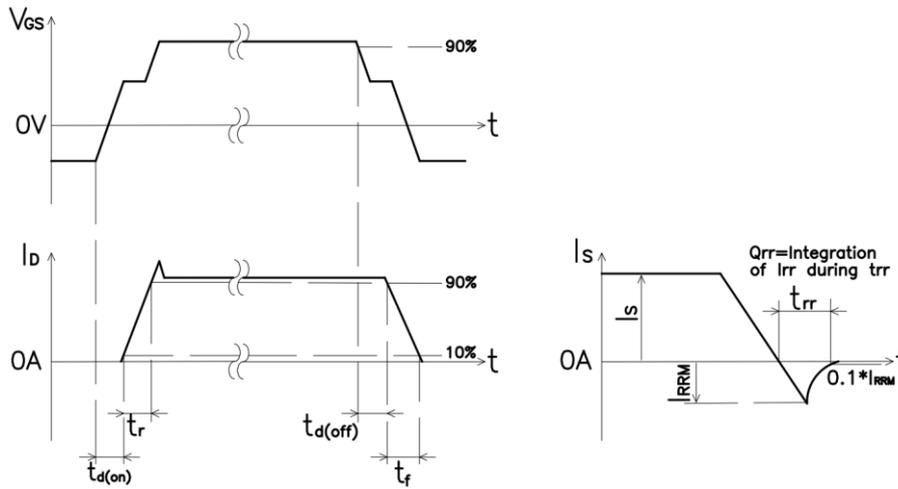
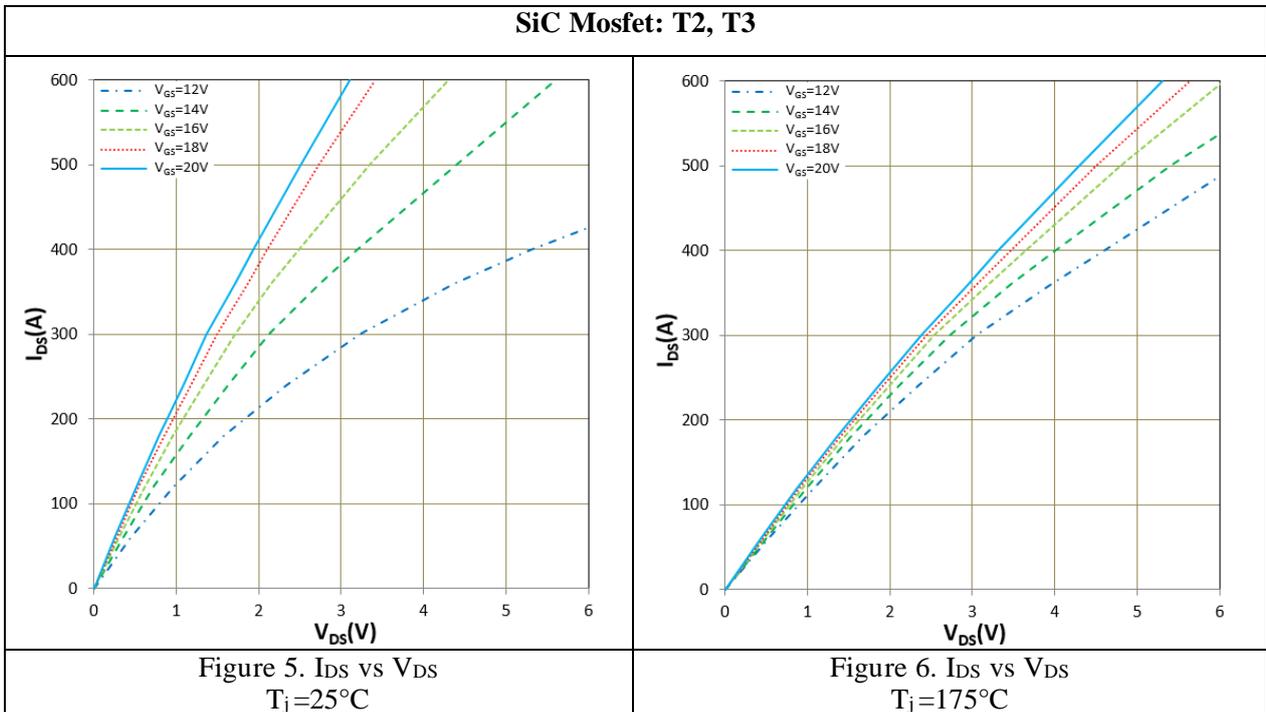


Figure 4. Switching time definition



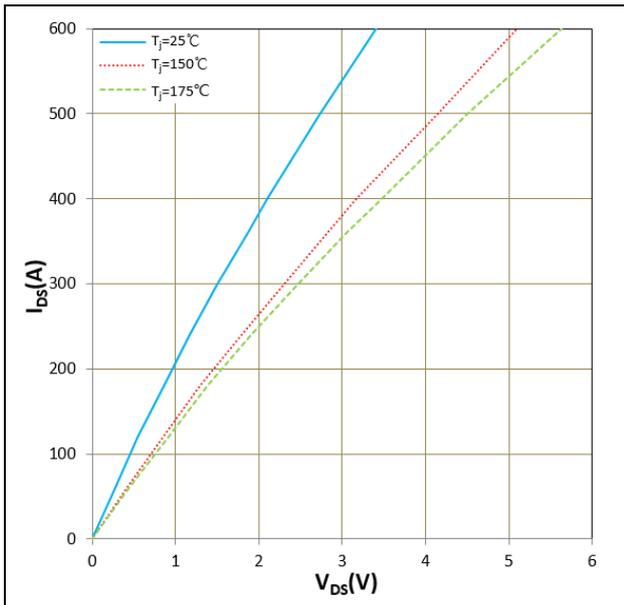


Figure 7.  $I_{DS}$  vs  $V_{DS}$   
 $V_{GS} = 18V$

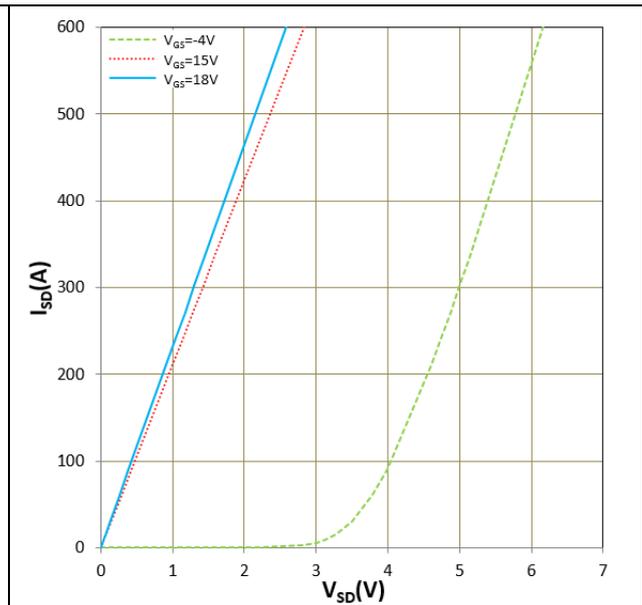


Figure 8.  $I_{SD}$  vs  $V_{SD}$  ( $V_F$ )  
 $T_j = 25^\circ C$

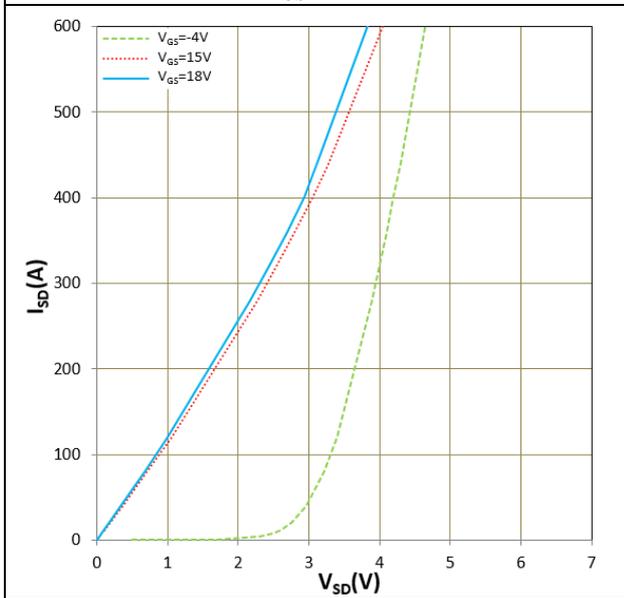


Figure 9.  $I_{SD}$  vs  $V_{SD}$  ( $V_F$ )  
 $T_j = 150^\circ C$

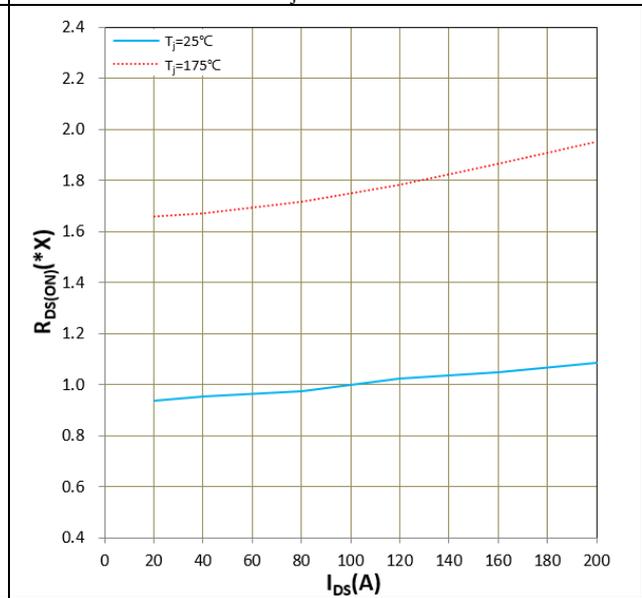


Figure 10.  $R_{DS(ON)}$  vs  $I_{DS}$   
 $1.0x = 4.3m\Omega$ ,  $V_{GS} = 18V$

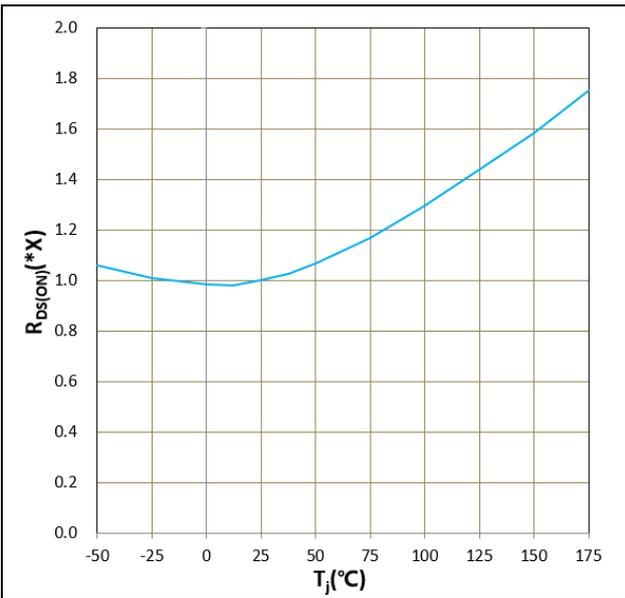


Figure 11.  $R_{DS(ON)}$  vs  $T_j$   
 $1.0x = 4.3m\Omega$ ,  $I_D = 300A$

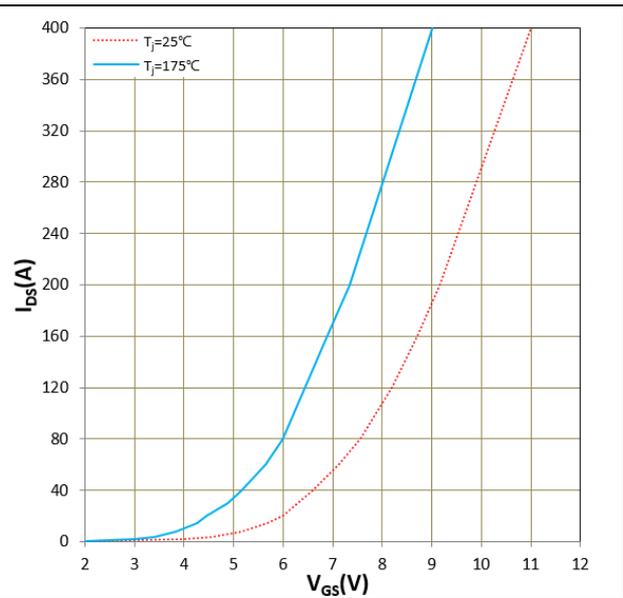


Figure 12.  $I_{DS}$  vs  $V_{GS}$   
 $V_{DS} = 10V$

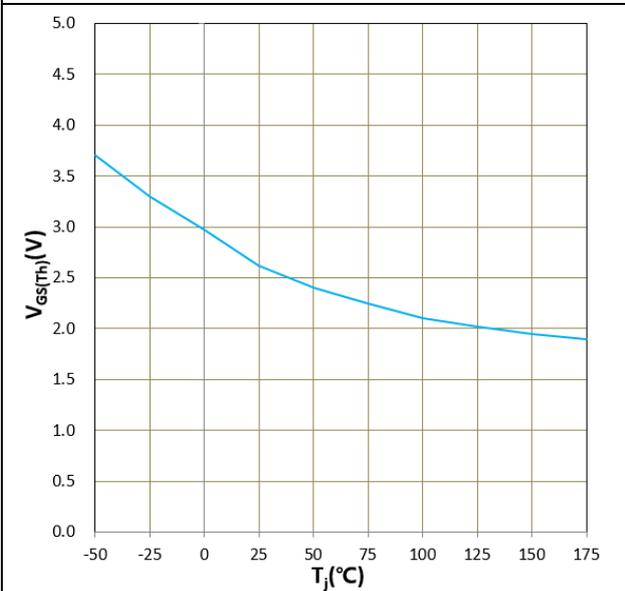


Figure 13.  $V_{GS(th)}$  vs  $T_j$   
 $V_{DS} = 10V$ ,  $I_{DS} = 80mA$

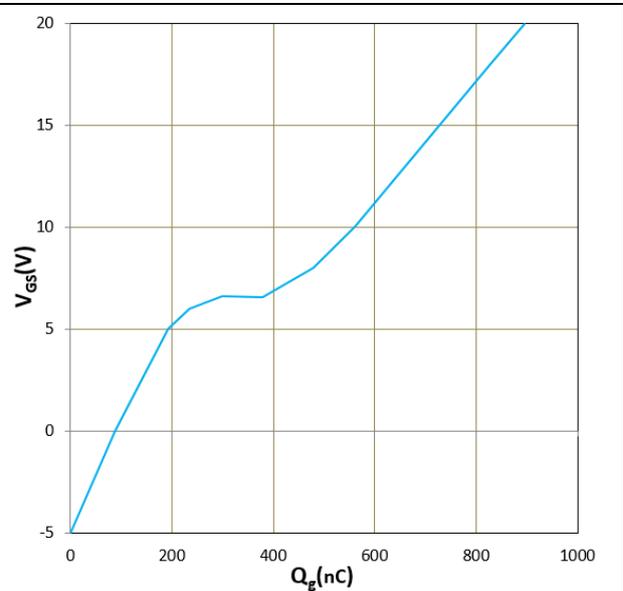


Figure 14. Gate charge  
 $I_{DS} = 200A$ ,  $I_{GS} = 0.4mA$ ,  $V_{DS} = 400V$

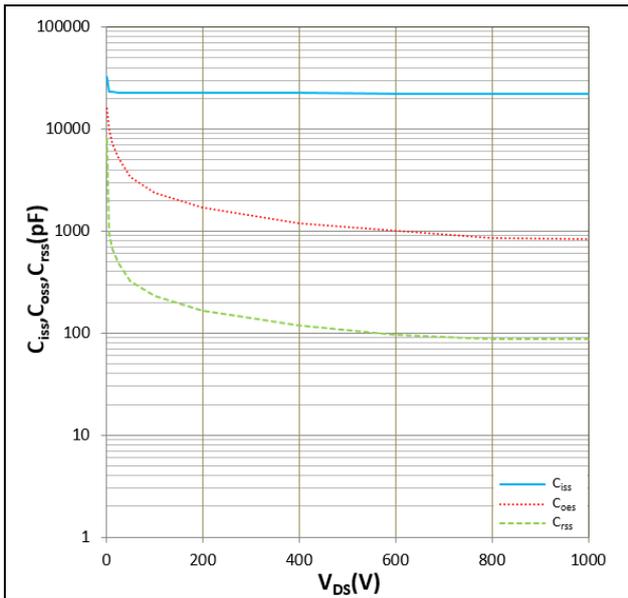


Figure 15.  $C_{iss}$ ,  $C_{oss}$ ,  $C_{rss}$  vs  $V_{CE}$   
 $V_{AC}=25mV$ ,  $f=1MHz$

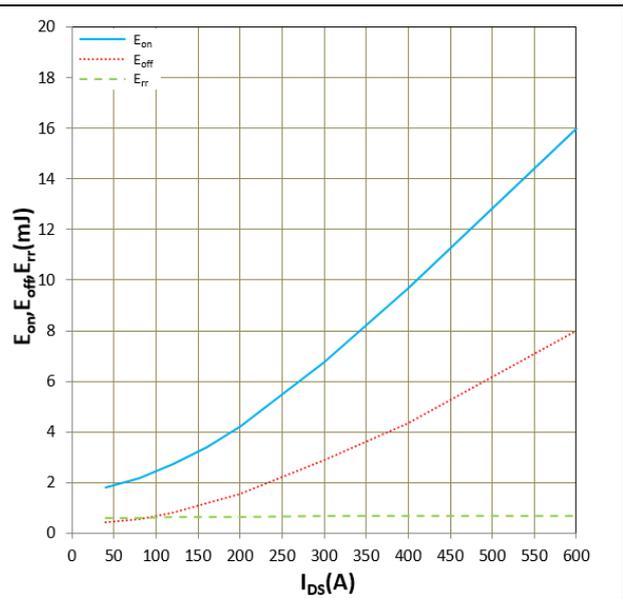


Figure 16.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_{DS}$   
 $T_j=25^\circ C$ ,  $V_{CC}=600V$ ,  $V_{GE}=+15/-4V$   
 $R_{GON}/R_{GOFF}=5.0\Omega$ , Inductive Load

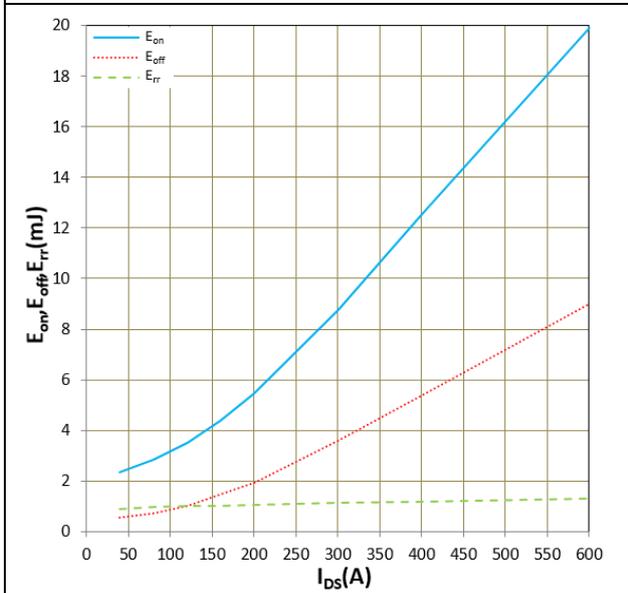


Figure 17.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $I_{DS}$   
 $T_j=150^\circ C$ ,  $V_{CC}=600V$ ,  $V_{GE}=+15/-4V$   
 $R_{GON}/R_{GOFF}=5.0\Omega$ , Inductive Load

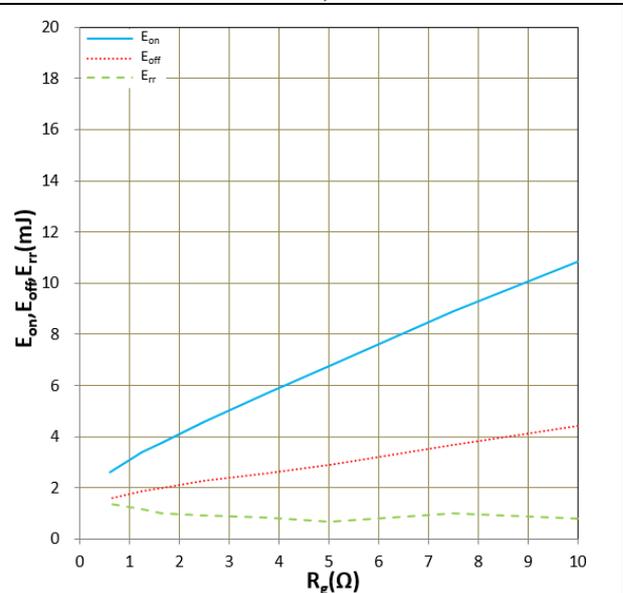


Figure 18.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j=25^\circ C$ ,  $V_{CC}=600V$ ,  $V_{GE}=+15/-4V$ ,  
 $I_D=300A$ , Inductive Load

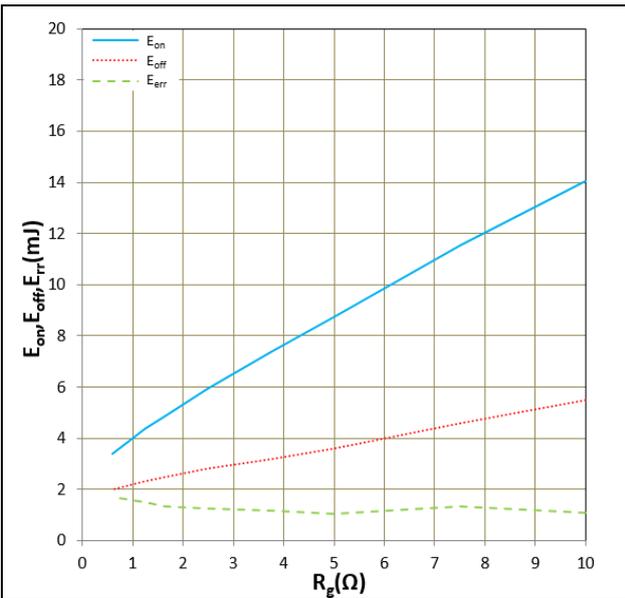


Figure 19.  $E_{on}$ ,  $E_{off}$ ,  $E_{rr}$  vs  $R_g$   
 $T_j=150^{\circ}\text{C}$ ,  $V_{CC}=600\text{V}$ ,  $V_{GE}=+15/-4\text{V}$ ,  
 $I_D=300\text{A}$ , Inductive Load

### IGBT: T1, T4, T5, T6 + Diode: D1, D4, D5, D6

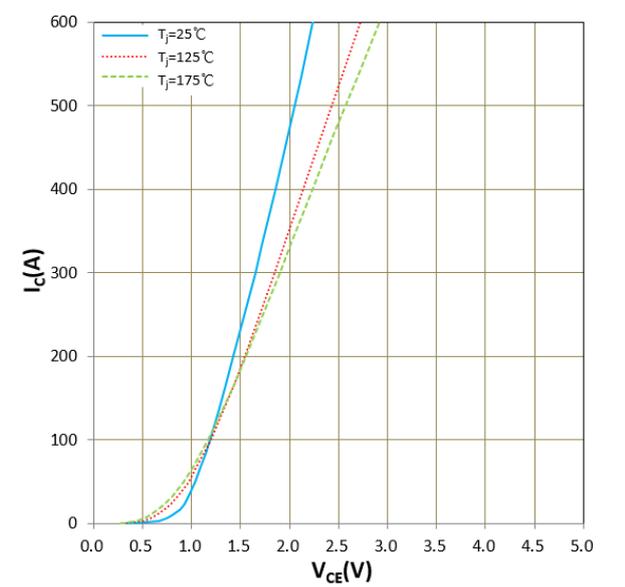


Figure 20.  $I_c$  vs  $V_{CE}$   
 $V_{GE}=15\text{V}$

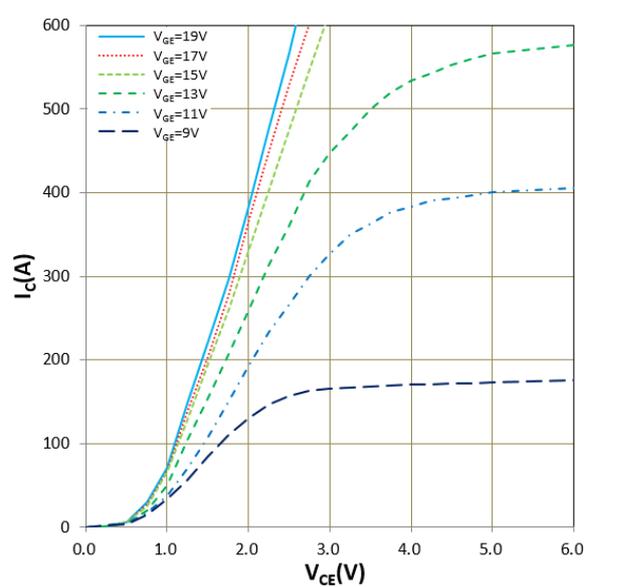


Figure 21.  $I_c$  vs  $V_{CE}$   
 $T_j=175^{\circ}\text{C}$

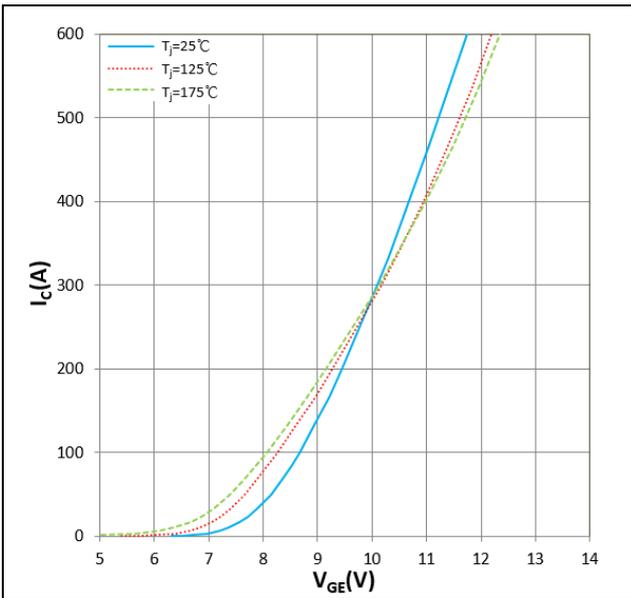


Figure 22.  $I_c$  vs  $V_{GE}$   
 $V_{CE} = 20V$

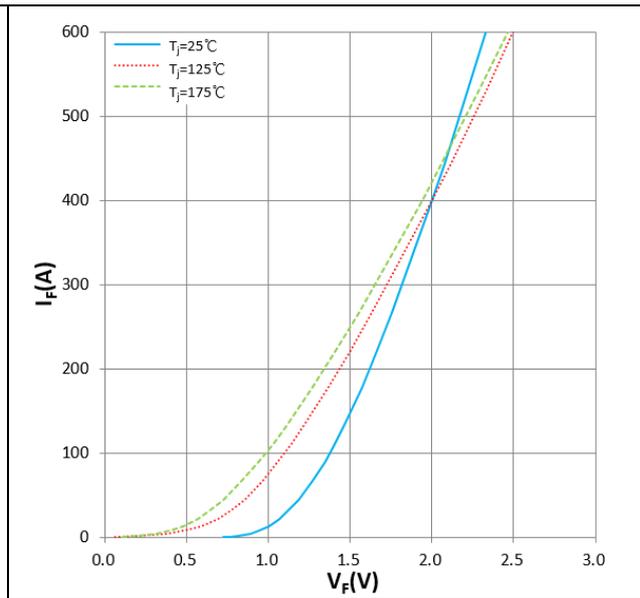


Figure 23.  $I_f$  vs  $V_f$

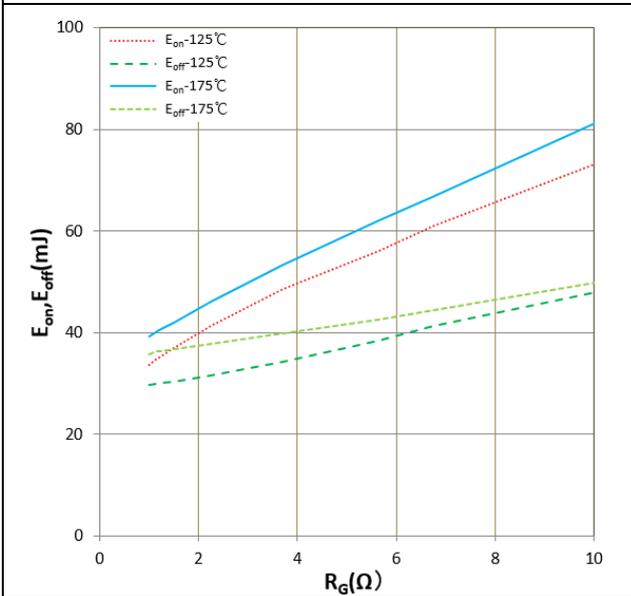


Figure 24.  $E_{on}$ ,  $E_{off}$  vs  $R_G$ (Typ)  
 $V_{CC} = 600V$ ,  $V_{GE} = +15V/-8V$ ,  $I_c = 300A$   
Inductive Load

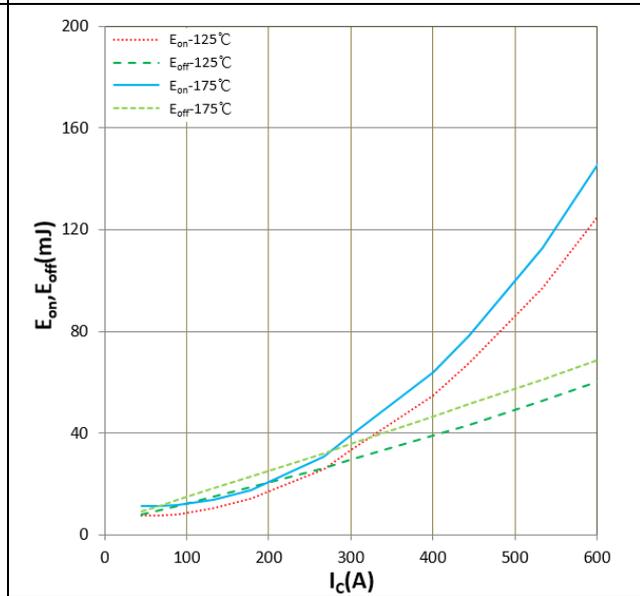


Figure 25.  $E_{on}$ ,  $E_{off}$  vs  $I_c$ (Typ)  
 $V_{CC} = 600V$ ,  $V_{GE} = +15V/-8V$ ,  $R_G = 1.0\Omega$   
Inductive Load

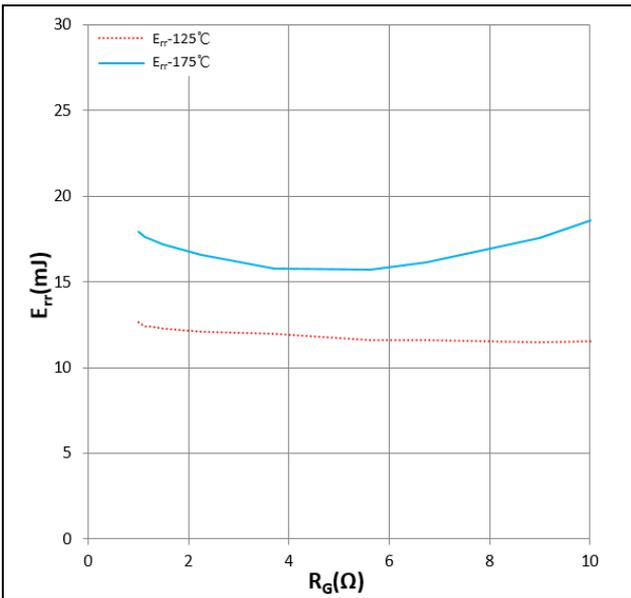


Figure 26.  $E_{rr}$  vs  $R_G$ (Typ)  
 $V_{CC}=600V$ ,  $V_{GE}=+15V/-8V$ ,  $I_F=300A$   
 Inductive Load

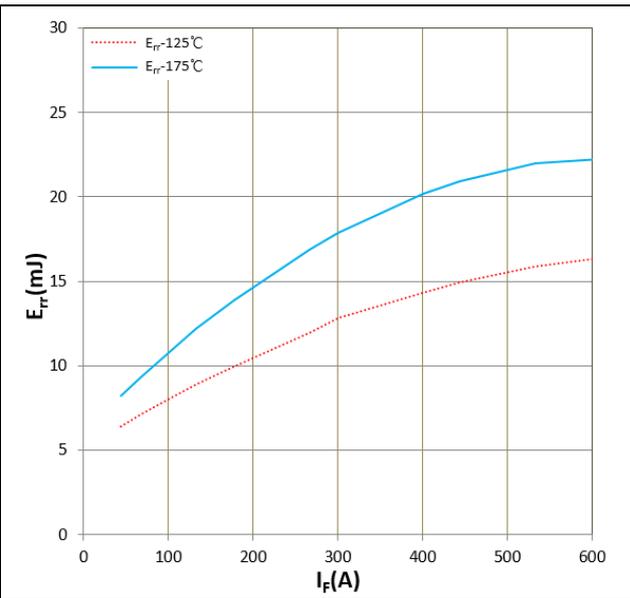


Figure 27.  $E_{rr}$  vs  $I_F$ (Typ)  
 $V_{CC}=600V$ ,  $V_{GE}=+15V/-8V$ ,  $R_G=1.0\Omega$   
 Inductive Load

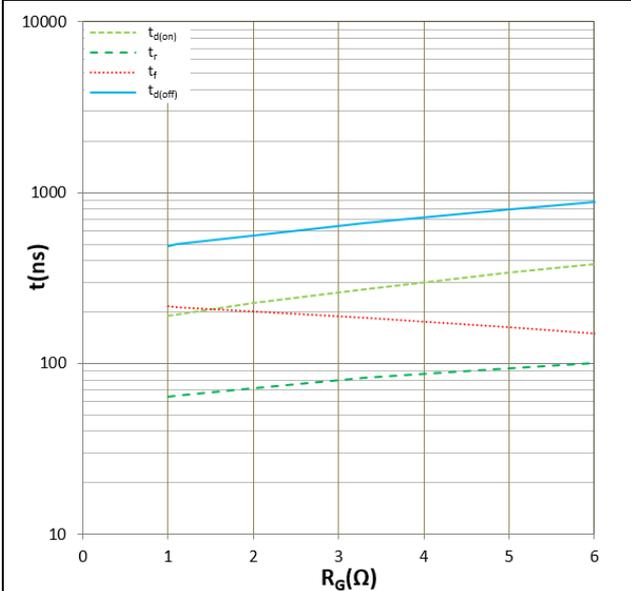


Figure 28. Switching time vs  $R_G$ (Typ)  
 $V_{CC}=600V$ ,  $V_{GE}=+15V/-8V$ ,  $I_C=300A$   
 $T_j=175^\circ C$ , Inductive Load

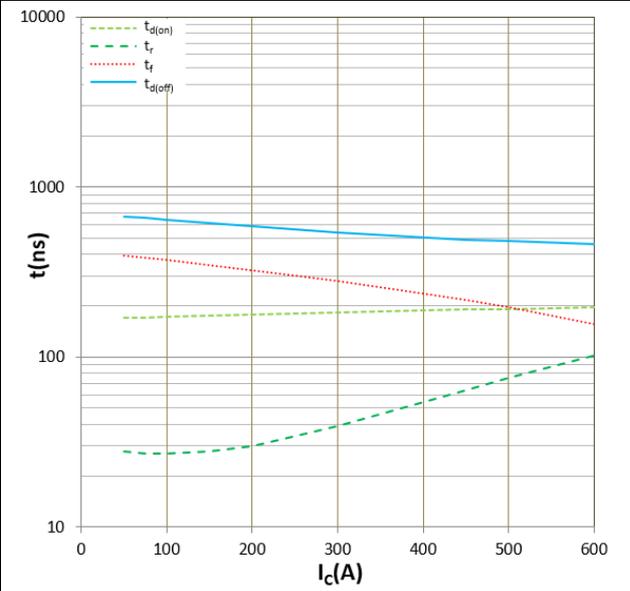


Figure 29. Switching time vs  $I_c$ (Typ)  
 $V_{CC}=600V$ ,  $V_{GE}=+15V/-8V$ ,  $R_G=1.0\Omega$   
 $T_j=175^\circ C$ , Inductive Load

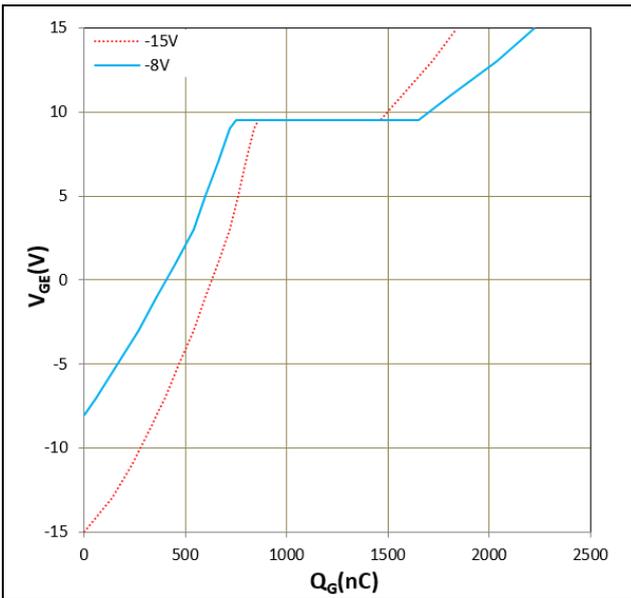


Figure 30. Gate charge

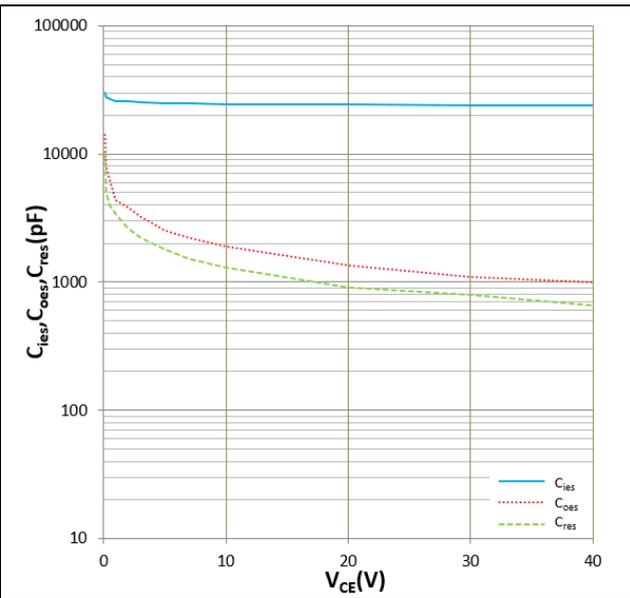
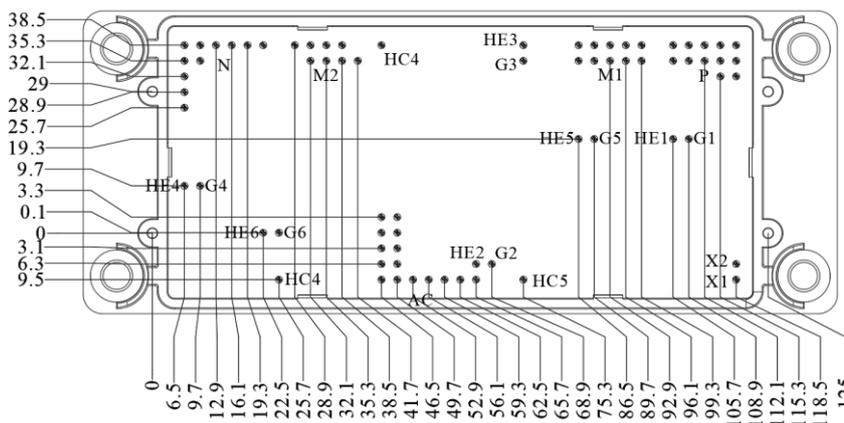
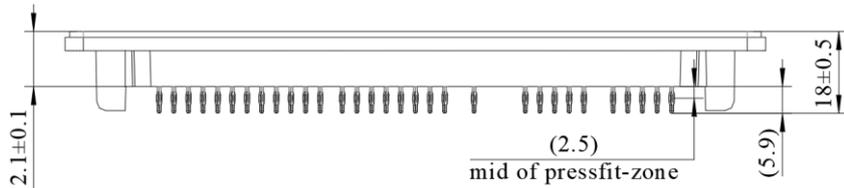
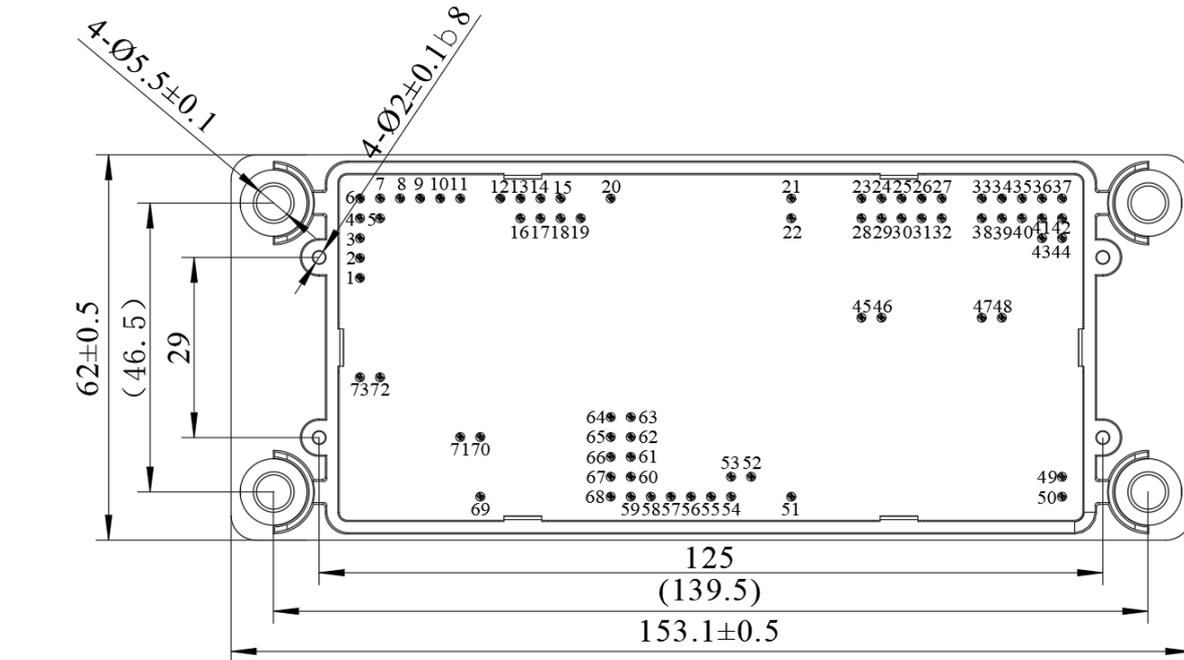


Figure 31.  $C_{ies}$ ,  $C_{oes}$ ,  $C_{res}$  vs  $V_{CE}$   
 $T_j = 25^\circ\text{C}$ ,  $f = 100\text{KHz}$

### Package dimensions



Pin	Pin table						
	X	Y	Pin	X	Y		
N	1	6.5	25.7	P	39	108.9	35.3
	2	6.5	28.9		40	112.1	35.3
	3	6.5	32.1		41	115.3	35.3
	4	6.5	35.3		42	118.5	35.3
	5	9.7	35.3		43	115.3	32.1
	6	6.5	38.5		44	118.5	32.1
	7	9.7	38.5		45	86.5	19.3
	8	12.9	38.5		46	89.7	19.3
	9	16.1	38.5		47	105.7	19.3
	10	19.3	38.5		48	108.9	19.3
	11	22.5	38.5		49	118.5	-6.3
	12	25.7	38.5		50	118.5	-9.5
	13	32.1	38.5		51	75.3	-9.5
	14	35.3	38.5		52	69.9	-6.3
	15	38.5	38.5		53	65.7	-6.3
	16	32.1	35.3		54	65.7	-9.5
	17	35.3	35.3		55	62.5	-9.5
	18	38.5	35.3		56	59.3	-9.5
	19	41.7	35.3		57	56.1	-9.5
M2	20	46.5	38.5	58	52.9	-9.5	
	21	75.3	38.5	59	49.7	-9.5	
	22	75.3	35.3	60	49.7	-6.3	
M1	23	86.5	38.5	61	49.7	-3.1	
	24	89.7	38.5	62	49.7	0.1	
	25	92.9	38.5	63	49.7	3.3	
	26	96.1	38.5	64	46.5	3.3	
	27	99.3	38.5	65	46.5	0.1	
	28	86.5	35.3	66	46.5	-1.1	
	29	89.7	35.3	67	46.5	-6.3	
	30	92.9	35.3	68	46.5	-9.5	
	31	96.1	35.3	69	25.7	-9.5	
	32	99.3	35.3	70	25.7	0.1	
	33	105.7	38.5	71	22.5	0.1	
	34	108.9	38.5	72	9.7	9.7	
	35	112.1	38.5	73	6.5	9.7	
	36	115.3	38.5				
	37	118.5	38.5				
	38	105.7	35.3				

### IMPORTANT NOTICE

This product data sheet describes the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively under the terms and conditions of the supply agreement. There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances. For information on the types in question, please contact the sales staff responsible for you.

Changes to this product data sheet are reserved.

Please contact the sales staff ([Sales@leapers-power.com](mailto:Sales@leapers-power.com)) for further information on the product, technology, delivery terms, conditions and prices.